



ACM Research Receives Multiple Advanced Packaging Equipment Orders from Leading Global Customers

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-Expands Advanced Packaging Platform Across Wafer-Level and Panel-Level Applications in Key Global Markets-

FREMONT, Calif., Feb. 26, 2026 (GLOBE NEWSWIRE) -- [ACM Research, Inc.](#) ("ACM") (NASDAQ: ACMR), a leading supplier of wafer and panel processing solutions for semiconductor and advanced packaging applications, today announced it has received multiple advanced packaging equipment orders from leading global semiconductor and technology customers.

This includes orders for:

- Multiple wafer-level advanced packaging systems from a leading global OSAT customer based in Singapore, with deliveries scheduled for the first quarter of 2026;
- A panel-level advanced packaging vacuum cleaning tool from a leading global semiconductor packaging manufacturer based outside mainland China, also scheduled for delivery in the first quarter of 2026; and
- Multiple wafer-level advanced packaging systems from a leading North America-based technology customer, with deliveries scheduled for later this year.

These recent customer wins represent a meaningful step forward in ACM's continued expansion of its advanced packaging platform and global customer base, reflecting growing industry recognition of ACM's differentiated technology portfolio across both wafer-level and panel-level applications.

"These global orders reinforce our leadership in wafer-level advanced packaging equipment while demonstrating the extension of our differentiated technologies into panel-level applications," said Dr. David Wang, President and Chief Executive Officer of ACM. "We remain committed to continued innovation to meet customers' increasingly demanding process and yield requirements, supported by a comprehensive product portfolio and global service infrastructure."

As semiconductor device complexity continues to increase, the industry is accelerating investment in scalable, high-performance manufacturing solutions to support artificial intelligence (AI), high-performance computing (HPC), and data center applications. Panel-level packaging is gaining strategic traction in these segments due to its scalability and cost efficiency.

ACM's wafer-level advanced packaging system orders include coating, developing, wet etching, stripping, cleaning and electroplating solutions for use in advanced packaging workflows, demonstrating continued international adoption of ACM's process technologies across critical manufacturing steps.

The panel-level order is for ACM's patent-pending Ultra C vac-p panel-level vacuum cleaning system, designed to address the stringent process requirements of advanced fan-out panel-level packaging (FOPLP) and fine-pitch interconnects. Leveraging vacuum-enhanced chemistry delivery, the system improves residue removal efficiency and process uniformity to support yield and reliability in complex 2.5D and 3D integration environments. The platform supports multiple panel formats, including 310 × 310 mm, 510 × 515 mm and 600 × 600 mm, enabling scalable manufacturing for next-generation device architectures.

Forward-Looking Statements

Certain statements contained in this press release are not historical facts and may be forward-looking statements within the meaning of the Private Securities Litigation Reform Act of 1995. Words such as "plans," "expects," "believes," "anticipates," "designed," and similar words are intended to identify forward-looking statements. Forward-looking statements are based on ACM management's current expectations and beliefs and involve a number of risks and uncertainties that are difficult to predict and that could cause actual results to differ materially from those stated or implied by the forward-looking statements. A description of certain of these risks, uncertainties and other matters can be found in filings ACM makes with the U.S. Securities and Exchange Commission, all of which are available at www.sec.gov. Because forward-looking statements involve risks and uncertainties, actual results and events may differ materially from results and events currently expected by ACM. Readers are cautioned not to place undue reliance on these forward-looking statements, which speak only as of the date hereof. ACM undertakes no obligation to publicly update these forward-looking statements to reflect events or circumstances that occur after the date hereof or to reflect any change in its expectations with regard to these forward-looking statements or the occurrence of unanticipated events.

About ACM Research, Inc.

ACM develops, manufactures and sells semiconductor process equipment spanning cleaning, electroplating, stress-free polishing, vertical furnace processes, track, PECVD, and wafer- and panel-level packaging tools, enabling advanced and semi-critical semiconductor device manufacturing. ACM is committed to delivering customized, high-performance, cost-effective process solutions that semiconductor manufacturers can use in numerous manufacturing steps to improve productivity and product yield. For more information, visit www.acmr.com.

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